

Public Products List

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PCI Title: Test site transfer from Amkor ATT3 to Amkor ATT6 for STBC02 and STBC03 devices in Flip Chip Package.

PCI Reference: AMS/21/13067

Subject: Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STBC02JR	STBC02AJR	STBC02BJR
STBC03JR		

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Process Change Information

Testing Plant Change: Amkor ATT3 → **Amkor ATT6**

AMS Analog Flip Chip devices on ETS-364 testers

STBC02 and STBC03 products

August, 2021

Introduction

- In agreement with Amkor (subcon) testing strategy, the ST AMS Analog testing capacity in Amkor Taiwan on Flip-Chip devices will be consolidated in the ATT6 (T6) site: testers currently located in ATT3 (T3) site will be relocated in ATT6 (see next page for details)
- T6 EWS plant is qualified by ST since September 2018
 - ST MCD production is running in T6 since Q3'18 (T2000 tester)
 - ST AMS IMG production is running in T6 since Q2'19 (UFLEX tester)
 - ST AMS Analog Divisions are progressively moving the testing on ETS-364 testers to T6 from January 2021.
 - This capacity extension does only concern the EWS Testing step; BUMPING & DPS remain unchanged
- Testing qualification is based on test comparison results on a correlation wafer from specific products or Test-Vehicles from same product family
- ST New Product Introduction projects will be directly qualified in T6



AMKOR T6 | LOCATION

Amkor T6 – Location



T3, Hukou Township, Hsinchu County



T6, Taoyuan City, Longtan District



- Over 130 probe testers has already moved into T6 from T3
- Almost all of test expertise and resources have moved to T6
- Continuous capacity increasement in T6 is on-going



Qualification Requirements and Buyoff Criteria

- Endurance & Repeatability Exercise
 - 1000x looped test on same dice
 - Acceptance criteria: No die killing, Yield >= 95%
- Site2Site Correlation exercise
 - 50x looped test on same dice
 - Acceptance criteria: No variation larger than measurement error
- Correlation Exercise
 - 1 correlation wafer (same wafer & probe card before/after relocation)
 - Yield and Bin to Bin difference (before/after) < 3%
 - Mean of each parametric measurement (before/after) < 5% of spec range
 - STDV of each parametric measurement (before/after) < 1% of spec range



Risk assessment (1/2)

Description	Difference	Comment
BUMPING	No change	Flow is not changed
EWS	T6	It was T3 before
Plant Location	T6	All EWS will be managed upon production capacity requirements in T6 only
Test Cell ID (tester & prober)	No change	Test Cells identified for moving to T6 have been already qualified & used in production
Test Cell Configuration	No change	
Test HW (PRC / PIB)	No change	HW identified to be relocated to T6 has been already qualified & used in production
Product Codification	No change	No product codification change T6 is added as 2nd EWS test plant



Risk assessment (2/2)

Description	Amkor T3	Amkor T6	Comment
Test Floor Clean Room	72K ft2	88K ft2	Area Expansion
Particle Class	1K		No difference
Temperature	22°C +/- 2°C		No difference
Humidity	45 +/- 5% RH		No difference
HW System Management	ATMS (Amkor Tooling Management for both plants	No difference	
Production system	Same system on both plants (MES, ATMS, PM, ECN, MRB, C	No change	
Production server	Both plants use the same servers the	No change	



Probe Card Room Equipment

Equipment List	ATT3	ATT6 oto	Function
Barcode System		100	Establish barcode. Infrared sendors to read, all traceable parts placement
Measure Machine			Measure needle length / diameter / co-planarity
Sanding Machine		W. T.	Automatic sanding tips co-planarity
Manual Adjustment		THE STATE OF THE S	Adjustment needle
N2 Cabinet		Married - Conference on the Co	Preserve probe card / PIB , Nitrogen cupboard wafer, by the oxidizing of preventive inoculation
Solder Tool	S. L.		Component solder / de-solder



Risk assessment | Summary

ST classifies this change as a LOW RISK

- BUMPING & DPS remains unchanged
- EWS Test Cell configuration remains unchanged
- EWS Production System Environment in T6 is similar to T3 (Area expansion only)





Test site Transfer Qualification Report

STBC02 and STBC03 products in Flip-Chip30: Test site Transfer from Amkor ATT3 to Amkor ATT6

General Information

Product Lines UQ5501

DC-DC CONVERTERS Product Description P/N STBC02 and STBC03

AMS (Analog MEMS & Sensor **Product Group**

Group)

General Purpose Analog & RF **Product division**

Division

POWER MANAGEMENT

Flip-Chip30 **Package**

Locations				
EWS Test fab (current)	Amkor Taiwan (subcon) ATT3			
EWS Test fab (new)	Amkor Taiwan (subcon) ATT6			

DOCUMENT INFORMATION

Version	Date	Pages	Prepared by	Approved by	Comment
1.0	September 2021	6	Shierly Yee	Angelo Ferrigno	Qualification activities on UQ55 are positive. Results are extended to all STBC02 and STBC03 Commercial Product options tested in Amkor subcon.

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TEST SITE TRANSFER QUALIFICATION REPORT

A. Repeatability & Endurance

50 loop run and endurance 1000 loop run were performed. (Criteria >= 95%) Summary Results = Pass

B. Yield Comparison

Yield comparison between ATT3 & ATT6. (Criteria: Delta yield < = 3%)

	Testin		
Lot# / Wfr#	Wfr# ATT3 ATT6		Delta
5026F88 - 22	94.12%	95.55%	1.43%

Summary Results = Pass

C. Bin Comparison:

Plant	AT					
Diffusion ID		5026F88				
Wafer ID		22				
Test Program						
Revision						
Qty In	46	97	4	4697		
Qty Out	44	21	4488			
Yield	94.12%		95.55%			
Bin name	Total Count	Percentage	Total Count	Percentage	Delta	%
Good	4421	94.06%	4488	95.55%	67	1.43%
Open/ Short	11	0.23%	13	0.28%	2	0.04%
Para	265	4.17%	69	1.47%		

Summary Results = failed. T6 has better yield than T3.

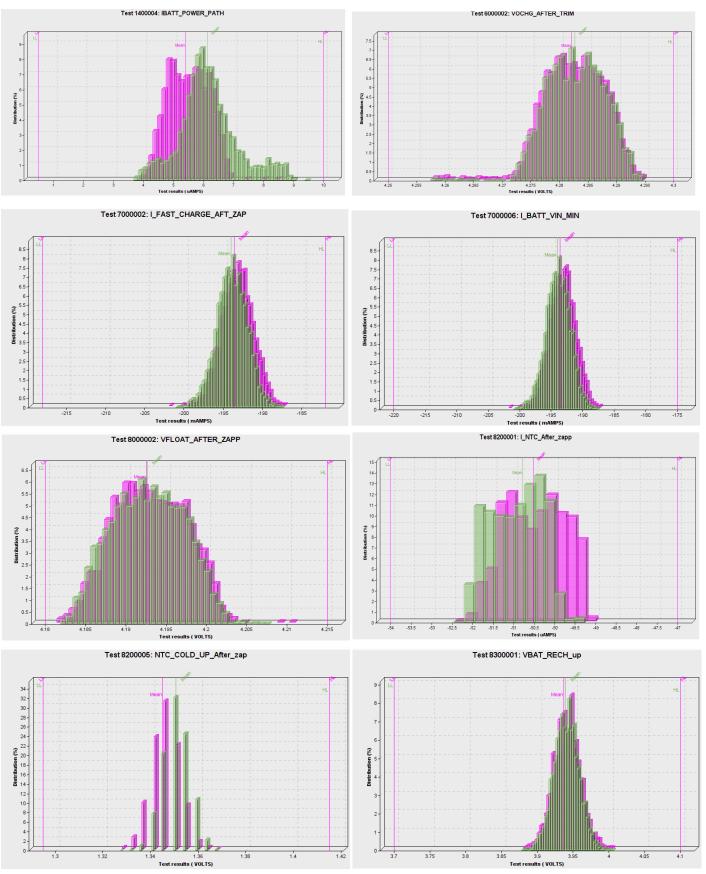
D. Correlation on the critical measures

Here a summary of critical measures on UQ55 line.

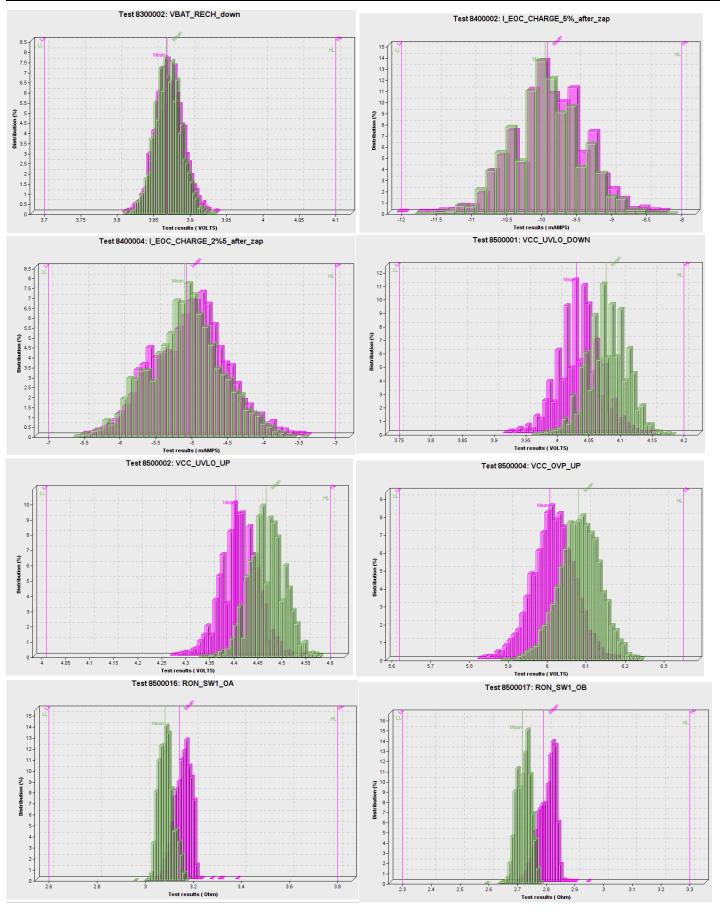
Data coming from present old facility (T3) is shown in green color and the data collected at new test facility (T6) is shown in pink color.

The data between the two test locations are consistent, confirming the goodness of the test setup. Results matches with qualification requirements.



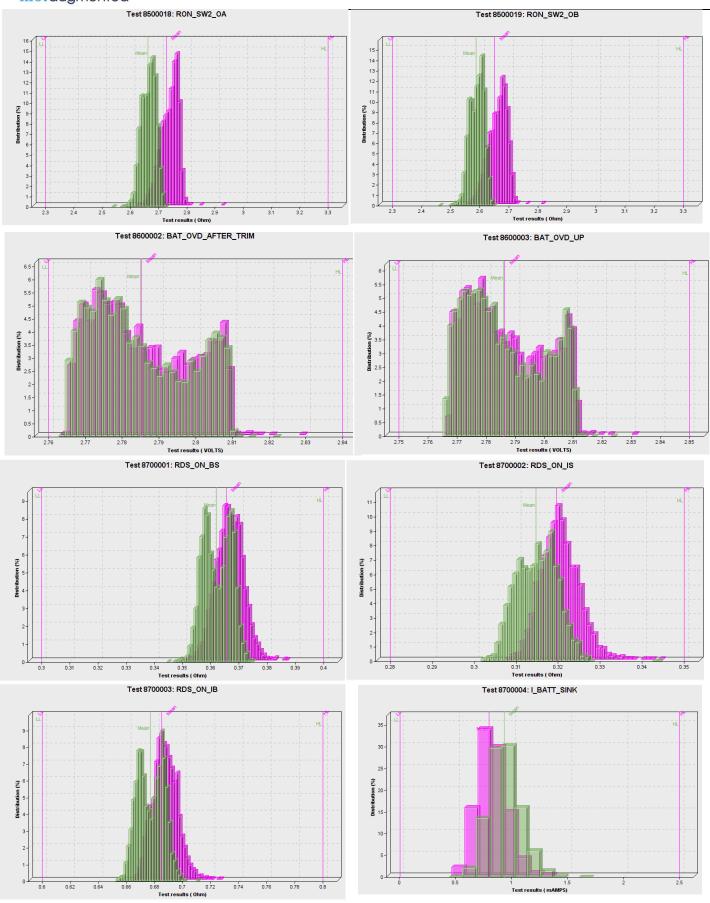




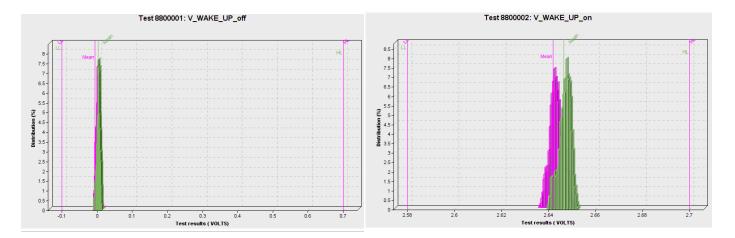




AMS (Analog, MEMS & Sensor Group) General Purpose Analog & RF Division Product Engineering and Operation







E. Overview of tester qualification result

- Yield is comparable.
- Repeatability and endurance test results are passed.
- Mean and Sigma study all parameters are evaluated; miscorrelation have been reviewed and justified.
- ATT6 is consider qualified to test UQ55 Product line in all STBC02 and STBC03 Commercial Product options.